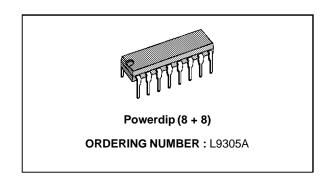


# **DUAL HIGH CURRENT RELAY DRIVER**

- HIGH OUTPUT CURRENT
- HYSTERESIS INPUT COMPARATOR WITH WIDE RANGE COMMON MODE OPERATION AND GROUND COMPATIBLE INPUTS
- INPUT COMPARATOR HYSTERESIS
- INTERNAL THERMAL PROTECTION WITH HYSTERESIS
- INTERNAL OUTPUT OVERVOLTAGE CLAMP-ING
- SINGLE SUPPLY VOLTAGE (3.5V up to 18V)



#### **DESCRIPTION**

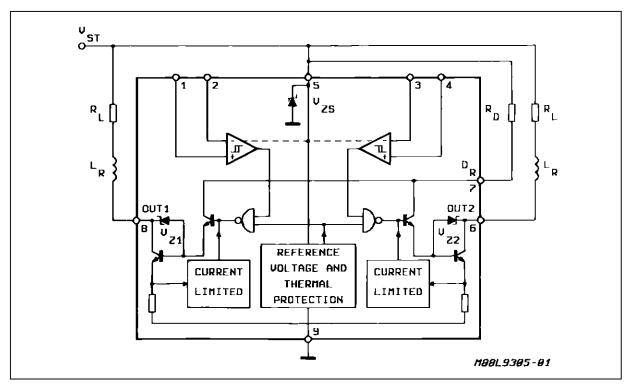
The L9305A is a monolithic interface circuit with differential input comparator and open collector output able to sink high current specifically to drive relays, lamps, d.c. motors.

Particular care has been taken to protect the device against destructive failures - short circuit of outputs to V<sub>S</sub>, output overvoltages, supply overvoltage.

A built in thermal shut-down switches off the device when the IC's internal dissipation becomes too great and the chip temperature exceeds a set security threshold.

A hysteresis input comparator increases the interface's noise immunity, allowing the correct use also in critical environments as automotive or industrial applications.

### **BLOCK DIAGRAM**



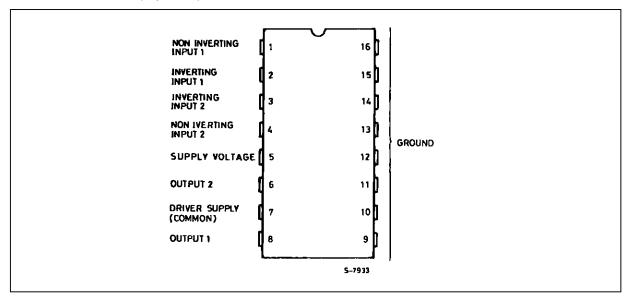
January 1992 1/6

### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>5</sub>	Supply Voltage	(*) 20	V
V <sub>7</sub>	Driver Supply Voltage	26	V
I <sub>ZS</sub>	Supply Zener Clamp Current (DC) (PULSED) (**)	30 80	mA mA
Vı	Comparator Input Voltage Range	- 0.2 to 24	V
VI	Differential Input Voltage	24	V
T <sub>j</sub> , T <sub>stg</sub>	Junction and Storage Temperature	– 55 to 150	°C
P <sub>tot</sub>	Power Dissipation at T <sub>amb</sub> = 85°C	928	mW
lo	Output Current	Int. limited	

<sup>(\*)</sup> The maximum allowed supply voltage without series resistors is limited by the built-in zener protection diodes (\*\*)  $T_{on} \le 2.5 \text{ ms}$ ; repetition time  $\ge 30 \text{ ms}$ .

## PIN CONNECTION (top view)



#### **THERMAL DATA**

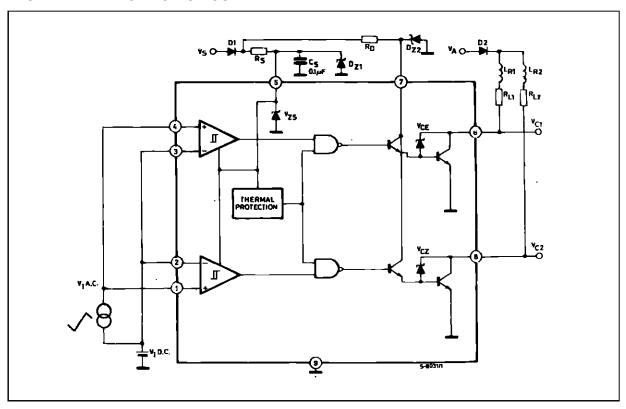
Symbol	Parameter	Value	Unit
R <sub>th j-pins</sub>	Thermal Resistance Junction to pins Max.	15	°C/W
R <sub>th j-amb</sub>	Thermal Resistance Junction to Ambient Max.	70	°C/W



**ELECTRICAL CHARACTERISTICS** ( $V_5$  = 14.4V,  $T_{amb}$  = 25°C; refer to block diagram unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>5</sub>	Supply Voltage		3.5		18*	V
Is "st.by"	Supply Current	$V_1^+ - V_1^- \ge 70 \text{mV}$		5	8	mA
I <sub>SON</sub>	Supply Current	$V_1^ V_1^+ > 70 \text{mV}$		18	30	mΑ
V <sub>CZ</sub>	Output Clamping Voltage (for each channel)	I <sub>OUT</sub> = 1A	20		27	V
$V_{ZS}$	Supply Voltage Clamp	$I_{ZS} = 10mA$	20		27	V
V <sub>IH</sub>	Comparator Hysteresis	$V_1^+ - V_1^- = 200 \text{mVpp}$ f = 1kHz	20		70	mV
Ι <sub>Β</sub>	Input Bias Current	$V^{+} = V^{-} = 0V$		0.2	1	μΑ
los	Input Offset Current	urrent $V^+ = V^- = 0V$		± 20	± 200	nA
CMR	Input Common Mode Range	$V_5 = 3.5V$ to 18V	0		V <sub>5</sub> – 1.6	V
I <sub>SC</sub>	Output Short Circuit Current for	$V_1$ $^  V_1$ $^+$ $\geq$ 70mV $V_{out}$ = 16.5V $V_{out}$ = 6V			0.85	Α
	Each Channel				2.5	Α
I <sub>CD</sub>	Driver Transistor Current	$V_1^ V_1^+ \ge 70 \text{mV}$ DC			300	mA
	Capability	Pulsed (**)			600	mA
V <sub>CSAT</sub>	On Status Saturation Voltage	$V_1^ V_1^+ \ge 70 \text{mV}$ $I_{CD} = 100 \text{mA}$			1	V
		$I_{COUT} = 1.2A$				
l <sub>OL</sub>	Output Leakage Current	$V_1^+ - V_1^- \ge 70 \text{mV}$			250	μΑ

## **TEST AND APPLICATION CIRCUIT**



<sup>\*</sup>  $T_{ON} \le 2.5 \text{ ms}$ ; repetition time  $\ge 30 \text{ ms}$ .

\*\* The maximum allowed supply voltage without limiting resistors is limited by the built-in protection zener diodes see  $V_{CZ}$ ,  $V_{ZS}$ Spec. velues.

#### **APPLICATION INFORMATIONS** (refer to application circuit)

D1 and D2 diodes are required only for reverse polarity protection.

If  $V_S$  may be higher than  $V_{ZS}$  a resistor  $R_S$  is necessary to limit the zener current  $I_{ZS}$ . In order to determine  $R_S$  value the following equations can be used:

1) 
$$\frac{V_{S MAX} - V_{D1} - V_{ZS min}}{R_S} < I_{ZS MAX}$$

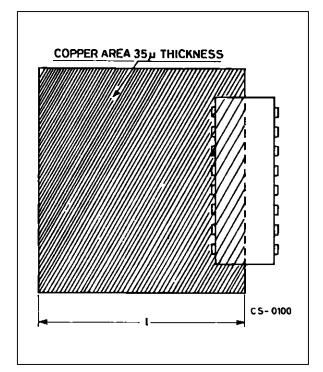
2)  $V_{S min} - V_{D1} - R_S - I_{SON MAX} > V_{ST min}$ where from  $T_{amb} = 25 \,^{\circ}\text{C}$ :

- V<sub>S MAX</sub> and V<sub>S min</sub> are the maximum and minimum values of power supply voltage
- V<sub>D1</sub> is the forward diode D1 voltage drop
- $V_{ZS min} = 20 V$
- I<sub>ZS MAX</sub> = 30 mA for d.c. mode and I<sub>ZS MAX</sub> = 80 mA for pulsed mode (see Absolute maximum ratings)
- $I_{SOM MAX} = 30 \text{ mA}$
- $V_{ST min} = 3.5 V$

If no  $R_S$  value can satisfy the system 1), 2) a more powerfull external zener  $D_Z = 18$  V is required.

Then 1) becomes:

Figure 2: Example of Heatsink Using PC Board Copper (I = 65 mm).



$$\frac{V_{S MAX} - V_{D1} - 18}{Rs} < I_{DZ MAX}$$

where I<sub>DZ MAX</sub> is the maximum allowed D<sub>Z</sub> current.

 $V_A$  voltage cannot be higher than 20 V otherwise output overvoltage protection may be activated. Morever  $V_A$  must be less than 16 V if short circuit protection is required.

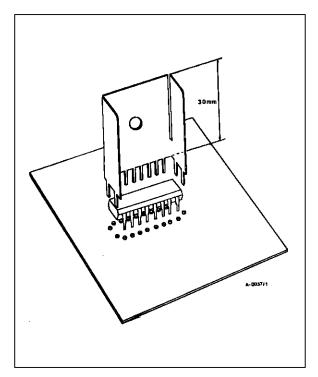
 $D_{Z2} = 22$  to 24 V is a mandatory for output 7 protection if V<sub>S</sub> may be higher than 26 V.

#### MOUNTING INSTRUCTION

The L9305A is assembled in a new plastic package, the Powerdip, in which 8 pins (from 9 to 16) are attached to the frame and remover the heat produced by the chip.

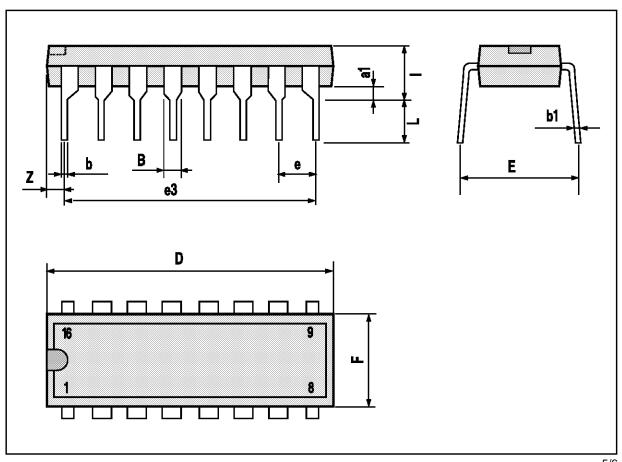
Figure 2 and 3 show two ways of heatsinking. In the first case, a PC board copper area is used as a heatsink I=65 mm. While in the second case, the device is soldered to an external heatsink. In both examples, the thermal resistance junction-ambient is 35 °C/W.

Figure 3: Example of an External Heatsink.



# POWERDIP16 PACKAGE MECHANICAL DATA

DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
В	0.85		1.40	0.033		0.055
b		0.50			0.020	
b1	0.38		0.50	0.015		0.020
D			20.0			0.787
E		8.80			0.346	
е		2.54			0.100	
e3		17.78			0.700	
F			7.10			0.280
ı			5.10			0.201
L		3.30			0.130	
Z			1.27			0.050



Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1994 SGS-THOMSON Microelectronics - All Rights Reserved

SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands - Singapore-Spain - Sweden - Switzerland - Taiwan - Thaliand - United Kingdom - U.S.A.

